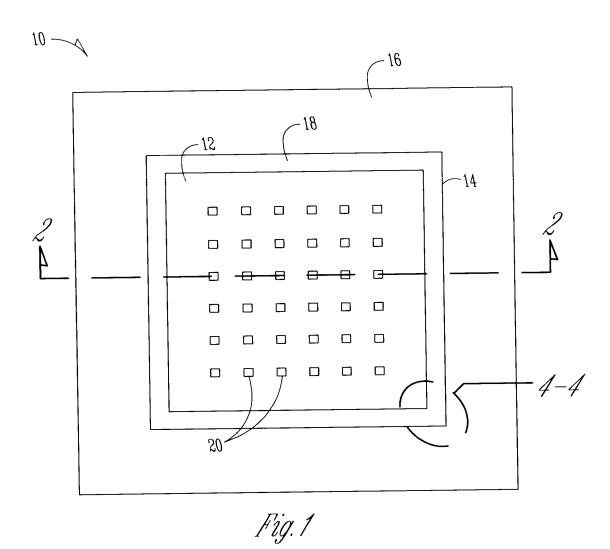
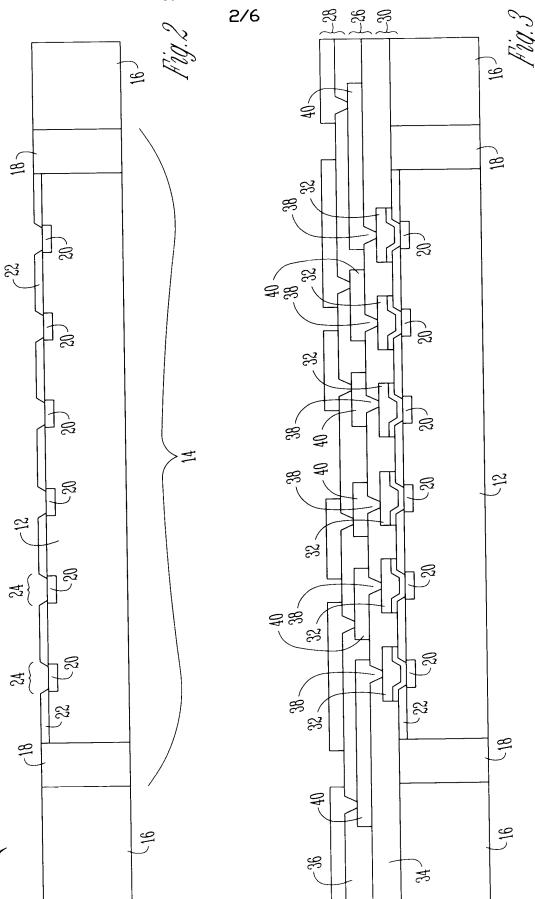
R USE IN





9

ENCAPSULATION MATERIAL WITH FIBROUS FILE OR USE IN MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towie DOCKET NO.: 884.415US1

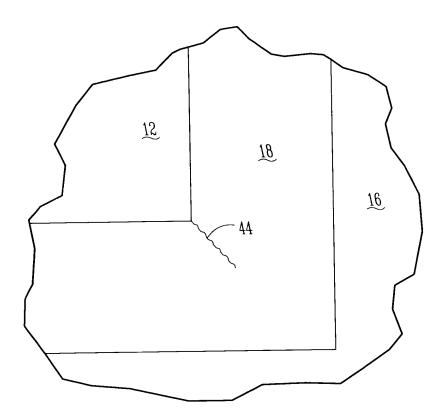


Fig. 4

ENCAPSULATION MATERIAL WITH FIBROUS FILL MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towle DOCKET NO.: 884.415US1 R USE IN TITLE: POLY

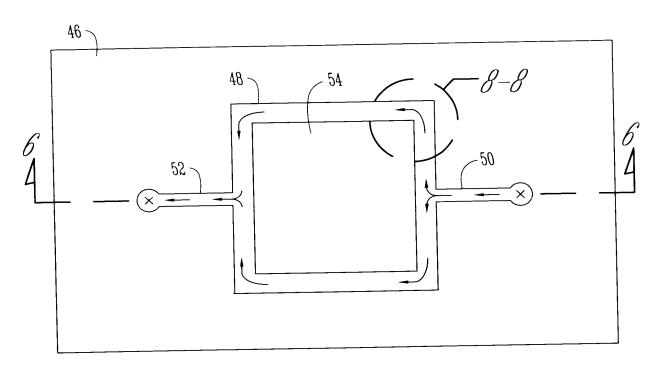


Fig. 5

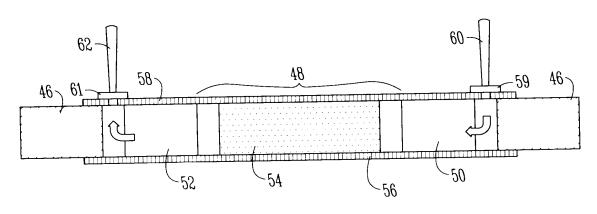


Fig. 6

ENCAPSULATION MATERIAL WITH FIBROUS FILE OR USE IN MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towle DOCKET NO.: 884.415US1 TITLE: POLY

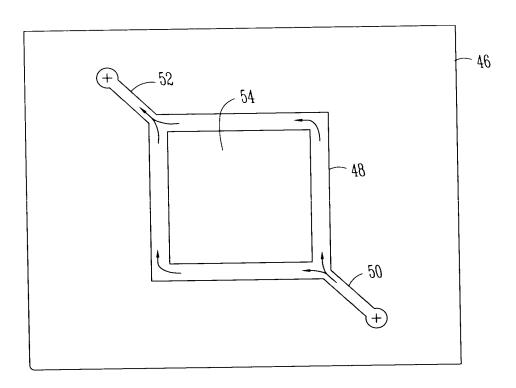


Fig. 7 -64 <u>46</u> 48 64~ <u>54</u> Fig. 8

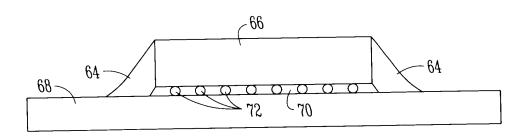


Fig. 9

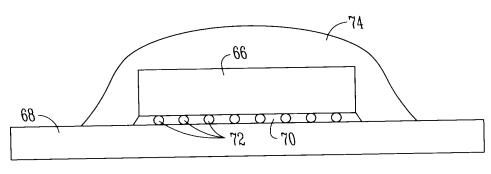


Fig. 10

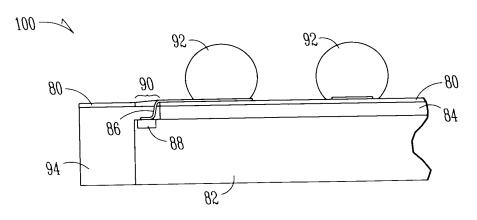


Fig. 11